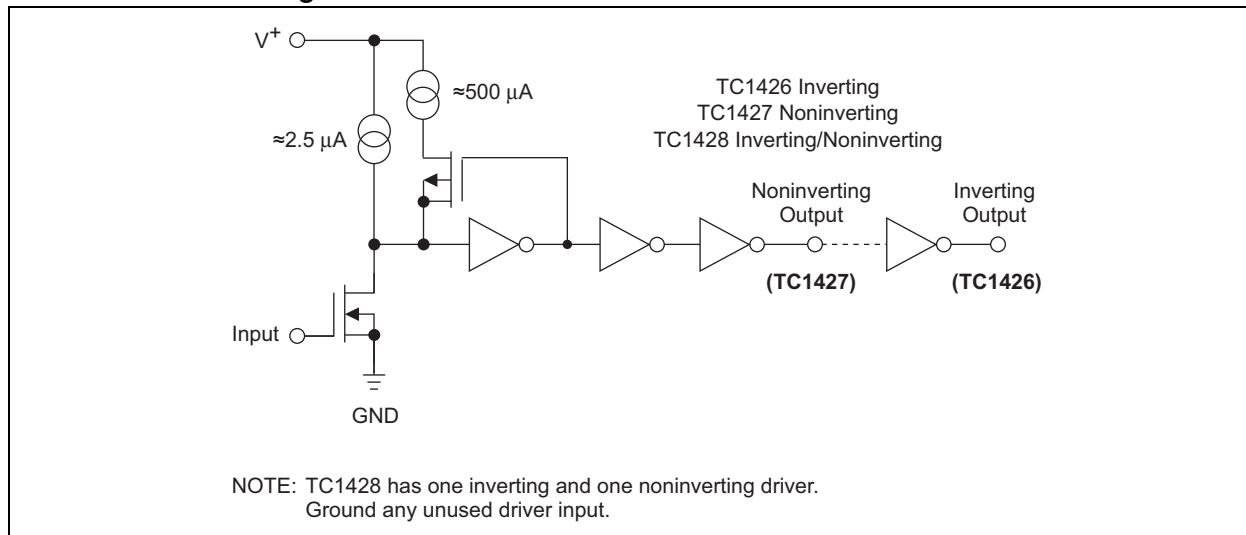


TC1426/TC1427/TC1428

Functional Block Diagram



TC1426/TC1427/TC1428

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings*

Supply Voltage	+18V
Input Voltage, Any Terminal	$V_{DD} + 0.3V$ to $GND - 0.3V$
Power Dissipation ($T_A \leq 70^\circ C$)	
PDIP	730 mW
SOIC	470 mW
Derating Factor	
PDIP	8 mW/ $^\circ C$
SOIC	4 mW/ $^\circ C$
Operating Temperature Range	
C Version	$0^\circ C$ to $+70^\circ C$
Storage Temperature Range	$-65^\circ C$ to $+150^\circ C$

*Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

TC1426/TC1427/TC1428 ELECTRICAL SPECIFICATIONS

Electrical Characteristics: $T_A = +25^\circ C$, with $4.5V \leq V_{DD} \leq 16V$, unless otherwise noted.						
Symbol	Parameter	Min	Typ	Max	Units	Test Conditions
Input						
V_{IH}	Logic 1, High Input Voltage	3	—	—	V	
V_{IL}	Logic 0, Low Input Voltage	—	—	0.8	V	
I_{IN}	Input Current	-1	—	1	μA	$0V \leq V_{IN} \leq V_{DD}$
Output						
V_{OH}	High Output Voltage	$V_{DD} - 0.025$	—	—	V	Figure 3-1, Figure 3-2
V_{OL}	Low Output Voltage	—	—	0.025	V	Figure 3-1, Figure 3-2
R_O	Output Resistance	—	12 8	18 12	Ω	$I_{OUT} = 10\text{ mA}$, $V_{DD} = 16V$
I_{PK}	Peak Output Current	—	1.2	—	A	
I_{REV}	Latch-Up Current Withstand Reverse Current	—	>500	—	mA	
Switching Time (Note 1)						
t_R	Rise Time	—	—	35	nsec	Figure 3-1, Figure 3-2
t_F	Fall Time	—	—	25	nsec	Figure 3-1, Figure 3-2
t_{D1}	Delay Time	—	—	75	nsec	Figure 3-1, Figure 3-2
t_{D2}	Delay Time	—	—	75	nsec	Figure 3-1, Figure 3-2
Power Supply						
I_S	Power Supply Current	—	—	9 0.5	mA	$V_{IN} = 3V$ (Both Inputs) $V_{IN} = 0V$ (Both Inputs)

Note 1: Switching times ensured by design.

TC1426/TC1427/TC1428

TC1426/TC1427/TC1428 ELECTRICAL SPECIFICATIONS (CONTINUED)

Electrical Characteristics: Over operating temperature range with $4.5V \leq V_{DD} \leq 16V$, unless otherwise noted.

Symbol	Parameter	Min	Typ	Max	Units	Test Conditions
Input						
V_{IH}	Logic 1, High Input Voltage	3	—	—	V	
V_{IL}	Logic 0, Low Input Voltage	—	—	0.8	V	
I_{IN}	Input Current	-10	—	10	μA	$0V \leq V_{IN} \leq V_{DD}$
Output						
V_{OH}	High Output Voltage	$V_{DD} - 0.025$	—	—	V	Figure 3-1, Figure 3-2
V_{OL}	Low Output Voltage	—	—	0.025	V	Figure 3-1, Figure 3-2
R_O	Output Resistance	—	15 10	23 18	Ω	$I_{OUT} = 10 \text{ mA}$, $V_{DD} = 16V$
I_{REV}	Latch-Up Current Withstand Reverse Current	—	>500	—	mA	
Switching Time (Note 1)						
t_R	Rise Time	—	—	60	nsec	Figure 3-1, Figure 3-2
t_F	Fall Time	—	—	40	nsec	Figure 3-1, Figure 3-2
t_{D1}	Delay Time	—	—	125	nsec	Figure 3-1, Figure 3-2
t_{D2}	Delay Time	—	—	125	nsec	Figure 3-1, Figure 3-2
Power Supply						
I_S	Power Supply Current	—	—	13 0.7	mA	$V_{IN} = 3V$ (Both Inputs) $V_{IN} = 0V$ (Both Inputs)

Note 1: Switching times ensured by design.

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PIN FUNCTION TABLE

Pin No. (8-Pin PDIP, SOIC)	Symbol	Description
1	NC	No connection.
2	IN A	Control input A, TTL/CMOS compatible logic input.
3	GND	Ground.
4	IN B	Control input B, TTL/CMOS compatible logic input.
5	OUT B	Output B, CMOS totem-pole output.
6	V _{DD}	Supply input, 4.5V to 16V.
7	OUT A	Output A, CMOS totem-pole output.
8	NC	No connection.

TC1426/TC1427/TC1428

3.0 APPLICATIONS INFORMATION

3.1 SUPPLY BYPASSING

Large currents are required to charge and discharge capacitive loads quickly. For example, charging a 1000 pF load to 16V in 25 nsec requires a 0.8A current from the device's power supply.

To ensure low supply impedance over a wide frequency range, a parallel capacitor combination is recommended for supply bypassing. Low-inductance ceramic MLC capacitors with short lead lengths (<0.5-in.) should be used. A 1.0 μ F film capacitor in parallel with one or two 0.1 μ F ceramic MLC capacitors normally provides adequate bypassing.

3.2 GROUNDING

The TC1426 and TC1428 contain inverting drivers. Individual ground returns for the input and output circuits or a ground plane should be used. This will reduce negative feedback that causes degradation in switching speed characteristics.

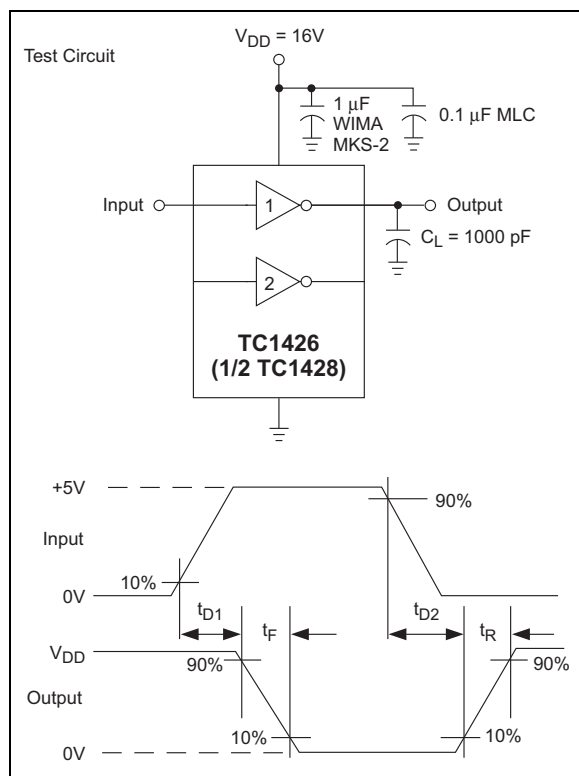


FIGURE 3-1: Inverting Driver Switching Time

3.3 INPUT STAGE

The input voltage level changes the no-load or quiescent supply current. The N-channel MOSFET input stage transistor drives a 2.5 mA current source load. With a logic '1' input, the maximum quiescent supply current is 9 mA. Logic '0' input level signals reduce quiescent current to 500 μ A maximum. **Unused driver inputs must be connected to VDD or GND.** Minimum power dissipation occurs for logic '0' inputs for the TC1426/TC1427/TC1428.

The drivers are designed with 100 mV of hysteresis. This provides clean transitions and minimizes output stage current spiking when changing states. Input voltage thresholds are approximately 1.5V, making a logic '1' input any voltage greater than 1.5V up to VDD. Input current is less than 1 μ A over this range.

The TC1426/TC1427/TC1428 may be directly driven by the TL494, SG1526/27, TC38C42, TC170 and similar switch-mode power supply integrated circuits.

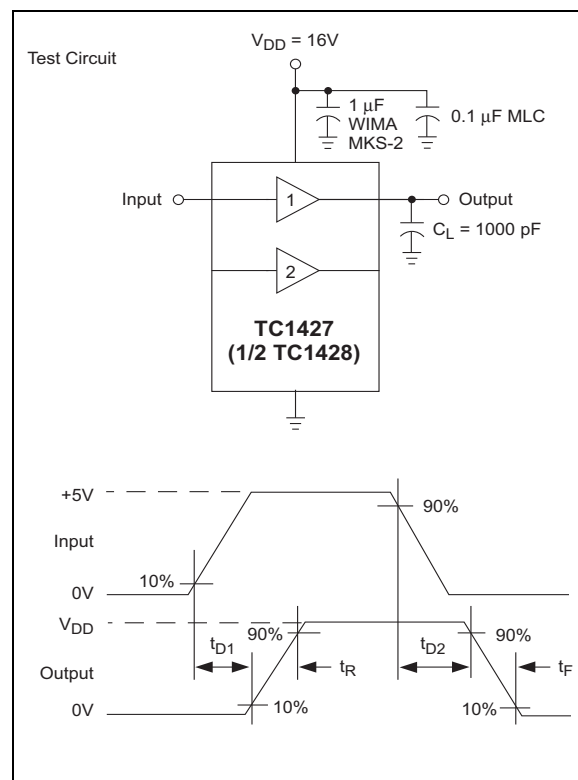
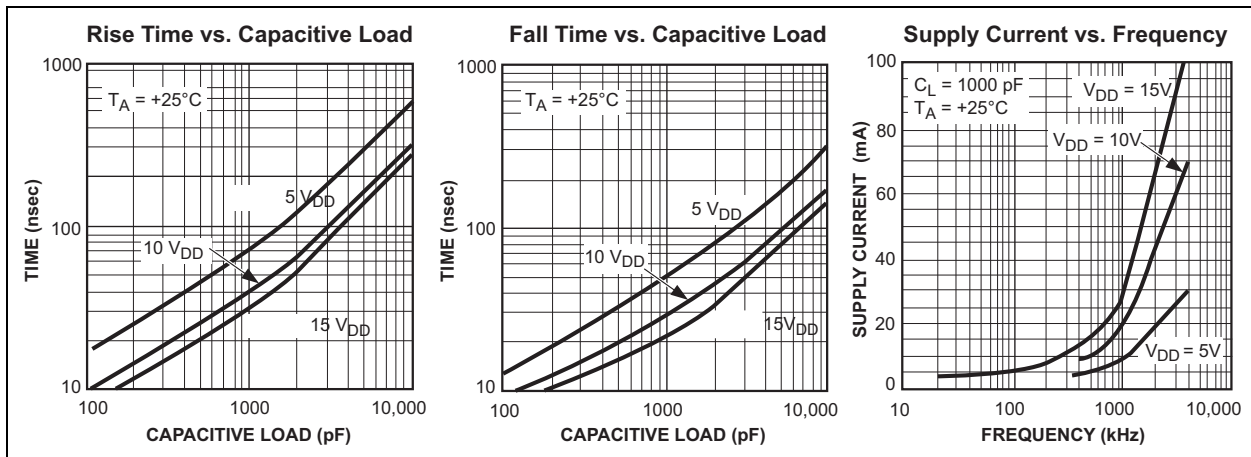
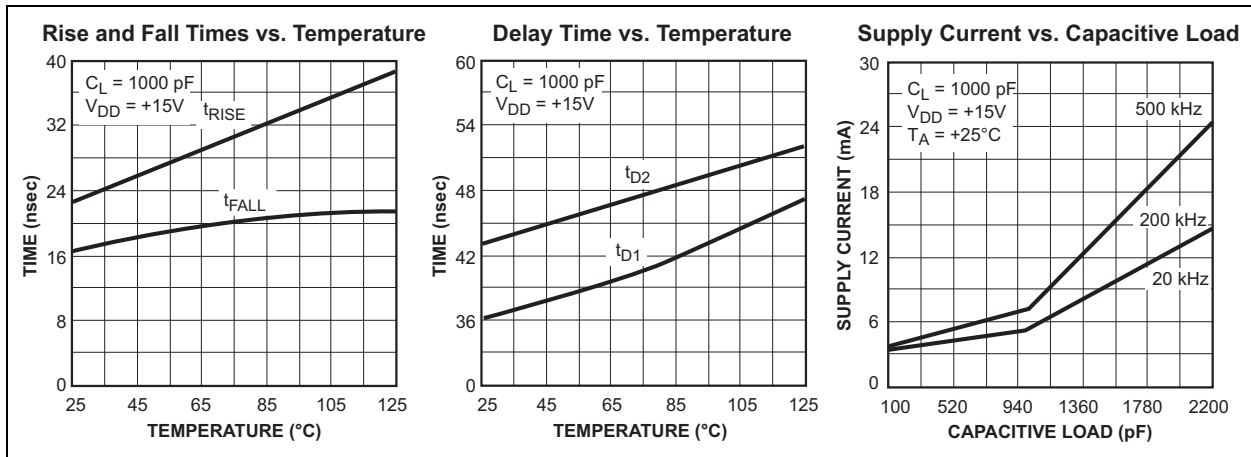
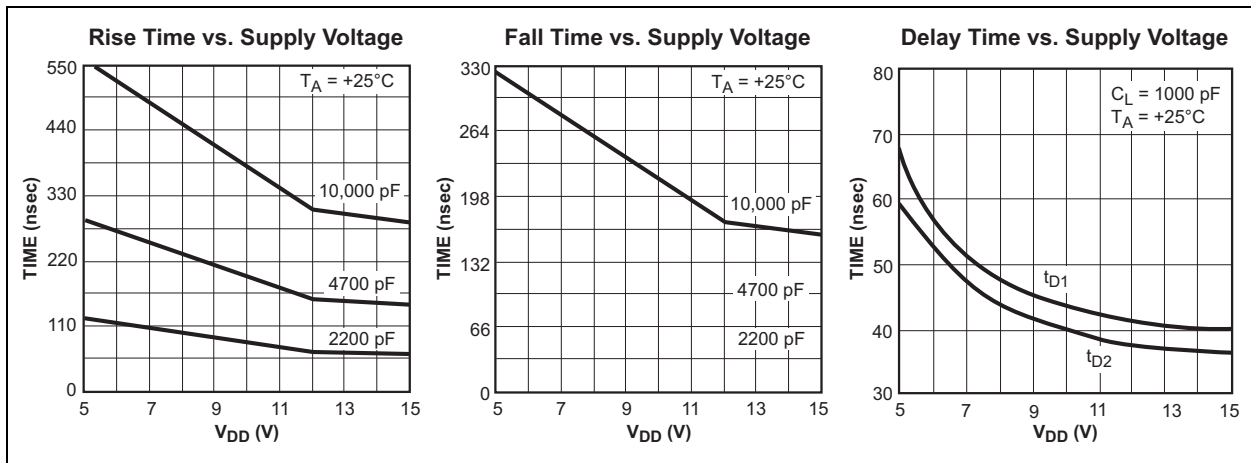


FIGURE 3-2: Noninverting Driver Switching Time

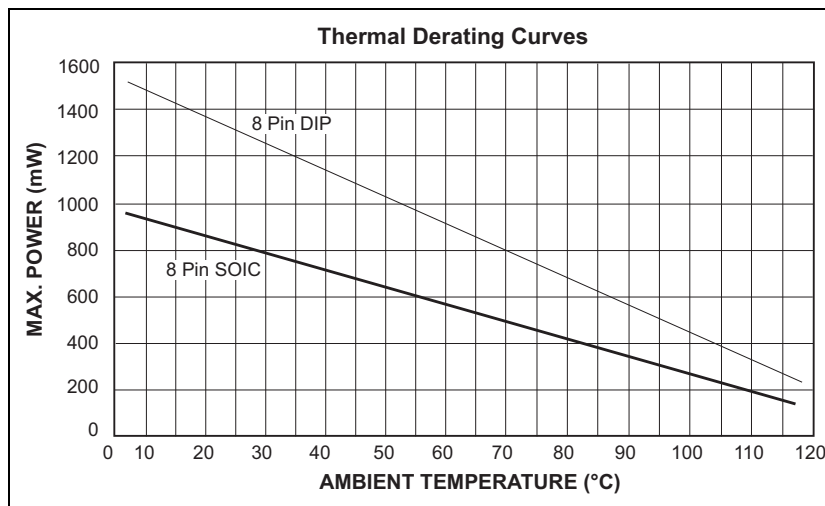
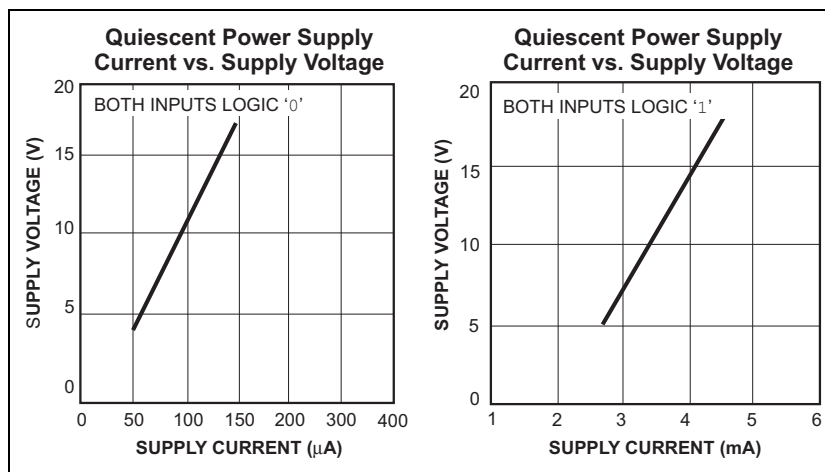
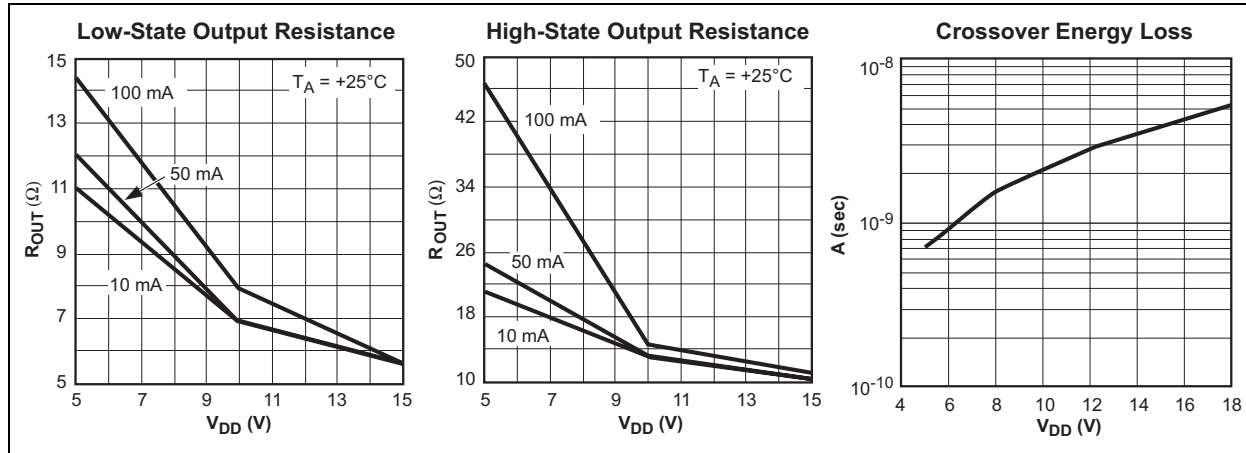
4.0 TYPICAL CHARACTERISTICS

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.



TC1426/TC1427/TC1428

TYPICAL CHARACTERISTICS (CONTINUED)



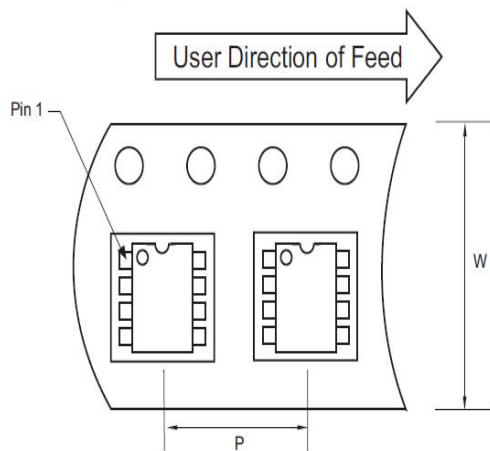
5.0 PACKAGING INFORMATION

5.1 Package Marking Information

Package marking data not available at this time.

5.2 Taping Form

Component Taping Orientation for 8-Pin MSOP Devices

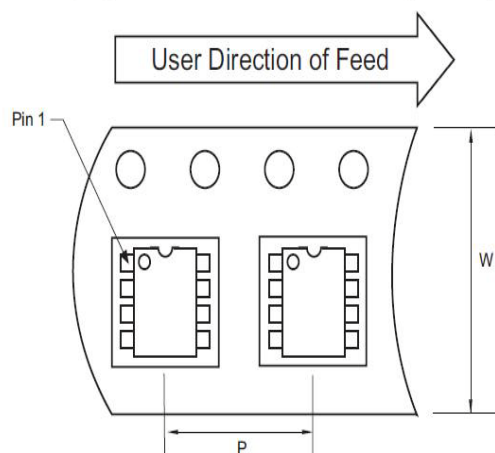


Standard Reel Component Orientation
for 713 Suffix Device

Carrier Tape, Number of Components Per Reel and Reel Size

Package	Carrier Width (W)	Pitch (P)	Part Per Full Reel	Reel Size
8-Pin MSOP	12 mm	8 mm	2500	13 in

Component Taping Orientation for 8-Pin SOIC (Narrow) Devices



Standard Reel Component Orientation
for 713 Suffix Device

Carrier Tape, Number of Components Per Reel and Reel Size

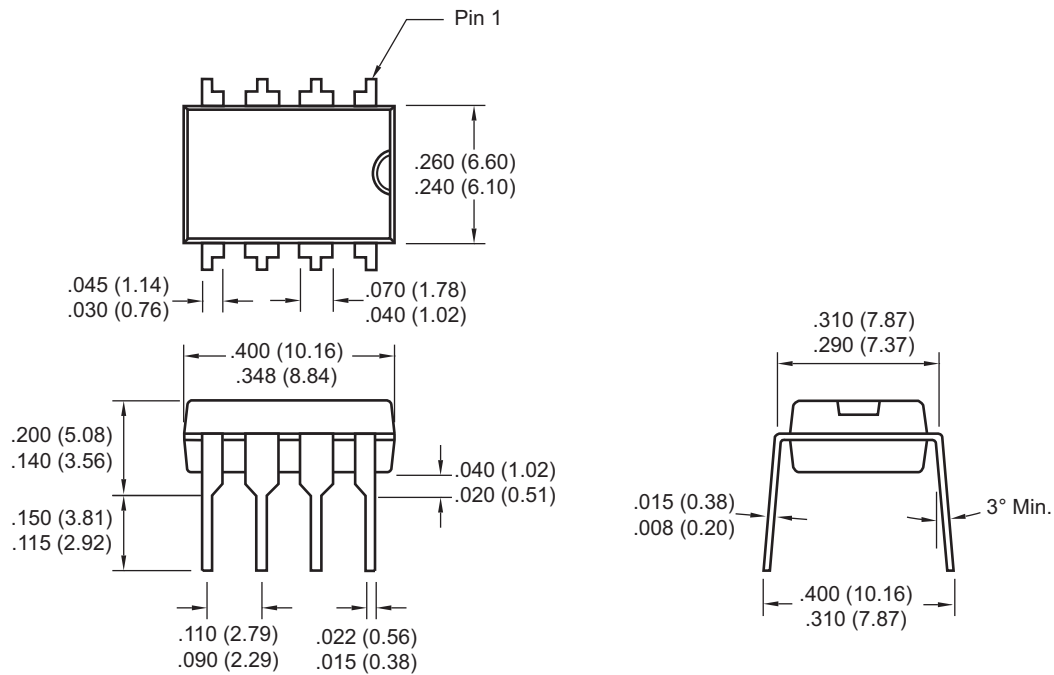
Package	Carrier Width (W)	Pitch (P)	Part Per Full Reel	Reel Size
8-Pin SOIC (N)	12 mm	8 mm	2500	13 in

TC1426/TC1427/TC1428

5.3 Package Dimensions

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

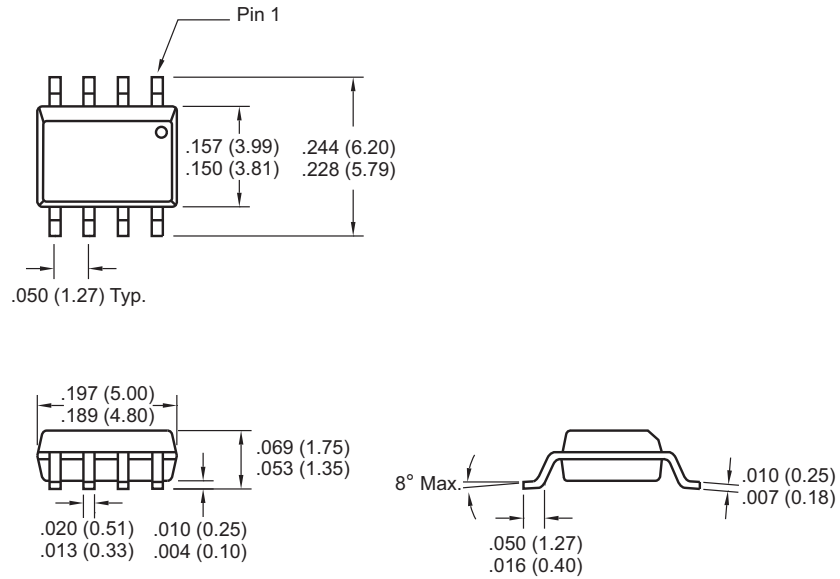
8-Pin Plastic DIP



Dimensions: inches (mm)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

8-Pin SOIC



Dimensions: inches (mm)

TC1426/TC1427/TC1428

6.0 REVISION HISTORY

Revision D (December 2012)

Added a note to each package outline drawing.

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